



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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BAR SAC0307

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PRODUCT DESCRIPTION

BAR SAC0307 provides the following product characteristics:

| | |
|--------------------|-------------------|
| Technology | Solder bar |
| Application | Pb-free soldering |

BAR SAC0307 alloy is designed for use as a Pb-free substitute for tin/lead alloys in most electronic assembly soldering applications. BAR SAC0307 is a low Ag version of the industry standard Tin-Silver-Copper Pb-free alloy.

FEATURES AND BENEFITS

- Best all-around Pb-free alternative
- Lowest Ag, Pb-free SAC alloy without undesirable additions
- Enhanced wetting characteristics
- Passes IPC/EIA J-STD-006B requirements
- Suitable for mixed technology builds

TYPICAL PROPERTIES

| ELEMENT | Weight % |
|---------------|--------------|
| Tin (Sn) | 98.9 to 99.1 |
| Silver (Ag) | 0.2 to 0.4 + |
| Copper (Cu) | 0.6 to 0.8 |
| Aluminum (Al) | ≤0.001 |
| Arsenic (As) | ≤0.03 |
| Gold (Au) | ≤0.005 |
| Bismuth (Bi) | ≤0.05 |
| Cadmium (Cd) | ≤0.002 |
| Iron (Fe) | ≤0.02 |
| Indium (In) | ≤0.03 |
| Nickel (Ni) | ≤0.007 |
| Lead (Pb) | ≤0.05 |
| Antimony (Sb) | ≤0.1 |
| Zinc (Zn) | ≤0.001 |

Solder Bar Typical Properties

| | |
|-------------------------------------|------------|
| Alloy | SAC0307 |
| Density, g/cm ³ | 7.4 |
| Alloy melting range, °C | 217 to 226 |
| Tensile Strength, N/mm ² | 29.5 |

PACKAGING

BAR SAC0307 is sold in economical 1000 lbs pallets.

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).

Not for Product Specifications

The technical information contained herein is intended for reference only. Please contact Henkel Technologies Technical Service for assistance and recommendations on specifications for this product.

Conversions

(°C x 1.8) + 32 = °F
kV/mm x 25.4 = V/mil
mm / 25.4 = inches
µm / 25.4 = mil
N x 0.225 = lb
N/mm x 5.71 = lb/in
N/mm² x 145 = psi
MPa x 145 = psi
N·m x 8.851 = lb·in
N·m x 0.738 = lb·ft
N·mm x 0.142 = oz·in
mPa·s = cP

Disclaimer

Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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